PRODUCT NO.	POSITION	REMARK	DIM "C"	DIM "D"
10053363-100LF	2 X 3 2	WITH KEY	54.61	54.46
10053363-200LF	2 X 3 2	WITHOUT KEY	N/A	N/A

NOTES:

I. MATERIALS:

HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL 94V-0 RATED, BLACK. TERMINAL; HIGH CONDUCTIVITY COPPER ALLOY,

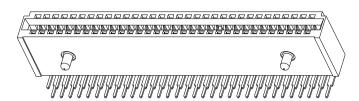
CONTACT AREA: 30u" GOLD OVER 50u" NICKEL UNDERPLATED. SOLDER TAIL: 100u" TIN OVER 50u" NICKEL UNDERPLATED.

2. PRODUCT PERFORMANCE SPEC. PER GS-12-259.

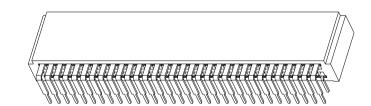
3. PACKAGE SPECIFICATION PER GS-14-937.

4. PART NUMBER 10053363-X00LF MEETS EUROPEAN UNION DIRECTIVE AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C±5°C PEAK TEMPERATURE FOR 5 SECONDS IN A REFLOW SOLDER APPLICATION WITH A CIRCUIT BOARD,

5. MANUFACTURER'S NAME, P/N AND DATE CODE TO APPEAR ON THIS SURFACE AS PER GS-24-007.



3



tolerance unless otherwise specified .X ± .30 $XX \pm .15$ XXX ± .08 X° ± 2° angles

В

Mark with				Material						Spec ref					
REV. Mat code									// tolerance		projection	n MM			
in area indicated Heattreat										\//		\blacksquare	V V		
by	Х			Plating/Finish				V							
				Dr	MAGGI	E WU	02/02/0) 5				s i z e	Scal	e	
rev		dr	date	Eng	DAVID	D TENG 05/26/05 Product family				t family		A 4		1.000	
A	T05-0117	-	05/31/05	Chr						Name	ECN				
В	T05-0130		06/16/05	Appr						Revision		REL Level			
С	T05-0162	DT	08/10/05		DOWED FOCE CARD CONNECTOR									-	
D	DG05-0287	SW	08/18/05	F	Ci .	<u>•</u>					OK 5 '	ΛΛΓ <u>2</u> 2	C 2	Rev.	
E	DG05-0521	SW	12/02/05	•		±	F	122 X	WIIH	I STAND-O		00533	63	G	
F	DG06-0321	RYAN	08/07/06		<i>-</i>	+					9				
G	DG06-0524	JULIA	12/26/06	Pro/	Efile	catalo	9 PDM	. Pa	v:G	CTATUC	Release	SIOMER Daine	sheet I o	f ₄ 3000	
							T DIVI	. 110	V. O	STATUS	incidase	Print	e a. Mar 1	4, 2004	

